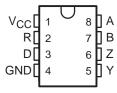
SLLS003E - OCTOBER 1985 - REVISED JUNE 1998

- Meets or Exceeds the Requirements of TIA/EIA-422-B, TIA/EIA-485-A, and ITU Recommendation V.11
- Bus Voltage Range . . . -7 V to 12 V
- Positive- and Negative-Current Limiting
- Driver Output Capability . . . 60 mA Max
- Driver Thermal-Shutdown Protection
- Receiver Input Impedance . . . 12 kΩ Min
- Receiver Input Sensitivity . . . ±200 mV
- Receiver Input Hysteresis . . . 50 mV Typ
- Operates From Single 5-V Supply
- Low Power Requirements

# D OR P PACKAGE (TOP VIEW)



# description

The SN75179B is a differential driver and receiver pair designed for balanced transmission-line applications and meets TIA/EIA-422-B, TIA/EIA-485-A, and ITU Recommendation V.11. It is designed to improve the performance of full-duplex data communications over long bus lines.

The SN75179B driver output provides limiting for both positive and negative currents. The receiver features high input impedance, input hysteresis for increased noise immunity, and input sensitivity of  $\pm 200$  mV over a common-mode input voltage range of -7 V to 12 V. The driver provides thermal shutdown for protection from line fault conditions. Thermal shutdown is designed to occur at a junction temperature of approximately 150°C. The SN75179B is designed to drive current loads of up to 60 mA maximum.

The SN75179B is characterized for operation from 0°C to 70°C.

#### **Function Tables**

#### DRIVER

INPUT	OUTPUTS				
D	Υ	Z			
Н	Н	L			
L	L	Н			

#### **RECEIVER**

DIFFERENTIAL INPUTS A – B	OUTPUT R
V <sub>ID</sub> ≥ 0.2 V	Н
$-0.2 \text{ V} < \text{V}_{\text{ID}} < 0.2 \text{ V}$	?
$V_{ID} \le -0.2 V$	L
Open	?

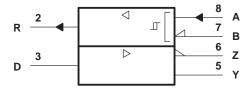
H = high level, L = low level, ? = indeterminate



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

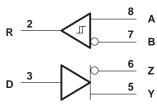


# logic symbol<sup>†</sup>

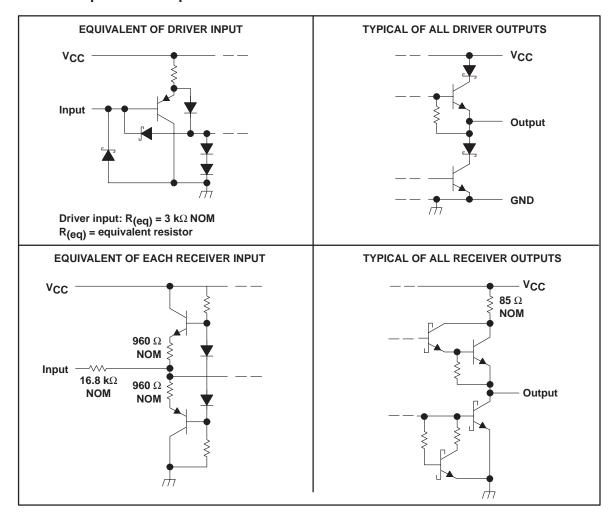


<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

# logic diagram (positive logic)



# schematics of inputs and outputs





# SN75179B DIFFERENTIAL DRIVER AND RECEIVER PAIR

SLLS003E - OCTOBER 1985 - REVISED JUNE 1998

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub> (see Note 1)	7 V
Voltage range at any bus terminal	
Differential input voltage, VID (see Note 2)	±25 V
Package thermal impedance, θ <sub>JA</sub> (see Note 3): D package	197°C/W
P package	104°C/W
Storage temperature range, T <sub>sto</sub>	65°C to 150°C
Storage temperature range, T <sub>stg</sub>	260°C

NOTES: 1. All voltage values, except differential input voltage, are with respect to network ground terminal.

- 2. Differential input voltage is measured at the noninverting input with respect to the corresponding inverting input.
- 3. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

# recommended operating conditions

			MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>			4.75	5	5.25	V
High-level input voltage, VIH	Driver		2			V
Low-level input voltage, V <sub>IL</sub>	Driver				0.8	V
Common-mode input voltage, V <sub>IC</sub>					12	V
Differential input voltage, V <sub>ID</sub>					±12	V
High level cutout current leve	Driver				-60	mA
High-level output current, IOH	Receiver				-400	μΑ
Low-level output current, I <sub>OL</sub> Driver  Receiver				60	A	
				8	mA	
Operating free-air temperature, TA			0		70	°C

<sup>&</sup>lt;sup>‡</sup> The algebraic convention, where the less positive (more negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage.



<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

# **DRIVER SECTION**

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CO	MIN	TYP <sup>†</sup>	MAX	UNIT	
VIK	Input clamp voltage	I <sub>I</sub> = -18 mA				-1.5	V
VO	Output voltage	IO = 0		0		6	V
V <sub>OD1</sub>	Differential output voltage	I <sub>O</sub> = 0		1.5		6	V
l V <sub>OD2</sub> l	Differential output voltage	$R_L = 100 \Omega$ ,	See Figure 1	1/2V <sub>OD1</sub> or 2 <sup>‡</sup>			٧
		$R_L = 54 \Omega$ ,	See Figure 1	1.5	2.5	5	V
V <sub>OD3</sub>	Differential output voltage	See Note 4		1.5		5	V
△l V <sub>OD</sub> l	Change in magnitude of common-mode output voltage§					±0.2	V
Voc	Common-mode output voltage	$R_L = 54 \Omega \text{ or } 100 \Omega,$	See Figure 1			3 -1	V
∆l V <sub>OC</sub> l	Change in magnitude of common-mode output voltage§					±0.2	V
IO	Output current	$V_{CC} = 0$ ,	$V_0 = -7 \text{ V to } 12 \text{ V}$			±100	μΑ
lН	High-level input current	V <sub>I</sub> = 2.4 V				20	μΑ
I <sub>Ι</sub> L	Low-level input current	V <sub>I</sub> = 0.4 V	•			-200	μΑ
laa	Short aircuit autaut aurrent	V <sub>O</sub> = −7 V				-250	mA
los	Short-circuit output current	$V_O = V_{CC}$ or 12 V	25			IIIA	
Icc	Supply current (total package)	No load			57	70	mA

 $<sup>\</sup>uparrow$  All typical values are at V<sub>CC</sub> = 5 V and T<sub>A</sub> = 25°C.

NOTE 4: See TIA/EIA-485-A, Figure 3.5, Test Termination Measurement 2.

# switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

PARAMETER		TEST CO	MIN	TYP	MAX	UNIT	
td(OD)	Differential output delay time	D: -54 O	See Figure 3		15	22	ns
t <sub>t</sub> (OD)	Differential output transition time	$R_L = 54 \Omega$ ,	See Figure 3		20	30	ns

#### **Symbol Equivalents**

DATA-SHEET PARAMETER	TIA/EIA-422-B	TIA/EIA-485-A
Vo	V <sub>oa</sub> , V <sub>ob</sub>	V <sub>oa</sub> , V <sub>ob</sub>
VOD1	Vo	Vo
V <sub>OD2</sub>	$V_t (R_L = 100 \Omega)$	$V_t (R_L = 54 \Omega)$
V <sub>OD3</sub>		V <sub>t</sub> (Test Termination Measurement 2)
Δ V <sub>OD</sub>	$  V_t - \overline{V}_t  $	$  V_t - \overline{V}_t  $
Voc	V <sub>os</sub>	V <sub>os</sub>
Δ VOC	$ V_{OS} - \overline{V}_{OS} $	$ V_{OS} - \overline{V}_{OS} $
los	$ I_{sa} ,  I_{sb} $	
IO	<sub>xa</sub>  ,    <sub>xb</sub>	l <sub>ia</sub> , l <sub>ib</sub>



 $<sup>\</sup>ddagger$  The minimum  $V_{\mbox{OD2}}$  with 100- $\Omega$  load is either 1/2  $V_{\mbox{OD2}}$  or 2 V, whichever is greater.

<sup>§</sup> Δ|V<sub>OD</sub>| and Δ|V<sub>OC</sub>| are the changes in magnitude of V<sub>OD</sub> and V<sub>OC</sub>, respectively, that occur when the input changes from a high level to a low level

#### RECEIVER SECTION

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONDITIONS				TYP <sup>†</sup>	MAX	UNIT
V <sub>IT+</sub>	Positive-going input threshold voltage	$V_0 = 2.7 V$ ,	$I_0 = -0.4 \text{ mA}$				0.2	V
VIT-	Negative-going input threshold voltage	$V_0 = 0.5 V$ ,	I <sub>O</sub> = 8 mA		-0.2‡			V
V <sub>hys</sub>	Hysteresis voltage (V <sub>IT+</sub> – V <sub>IT-</sub> )					50		mV
Vон	High-level output voltage	$V_{ID} = 200 \text{ mV},$	$I_{OH} = -400  \mu A$ ,	See Figure 2	2.7			V
VOL	Low-level output voltage	$V_{ID} = -200 \text{ mV},$	$I_{OL} = 8 \text{ mA},$	See Figure 2			0.45	V
1.	Line input current	Other input at 0 V,	See Note 5	V <sub>I</sub> = 12 V			1	mA
<u> </u>	Line input current	Other input at 0 v,	See Note 5	$V_I = -7 V$			-0.8	IIIA
rį	Input resistance				12			kΩ
los	Short-circuit output current				-15		-85	mA
ICC	Supply current (total package)	No load				57	70	mA

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

NOTE 5: Refer to TIA/EIA-422-B for exact conditions.

# switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<sup>t</sup> PLH	Propagation delay time, low- to high-level output	$V_{ID} = -1.5 \text{ V to } 1.5 \text{ V},$		19	35	ns
<sup>t</sup> PHL	Propagation delay time, high- to low-level output	C <sub>L</sub> = 15 pF, See Figure 4		30	40	ns

#### PARAMETER MEASUREMENT INFORMATION

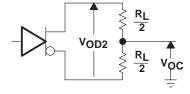


Figure 1. Driver V<sub>DD</sub> and V<sub>OC</sub>

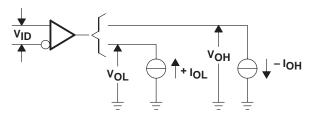
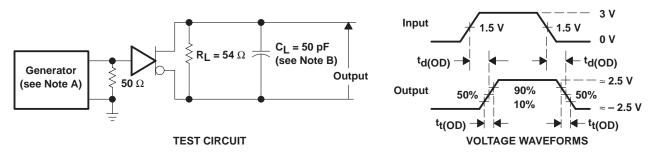


Figure 2. Receiver VOH and VOL

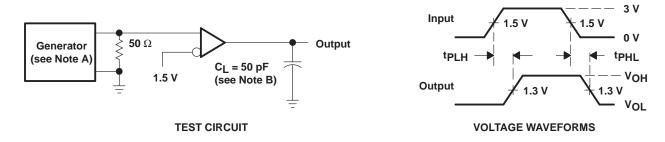
<sup>&</sup>lt;sup>‡</sup> The algebraic convention, where the less positive (more negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.

## PARAMETER MEASUREMENT INFORMATION (CONTINUED)



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_f \leq$  6 ns,  $t_f \leq$  7 ns,  $t_f \leq$  8 ns,  $t_f \leq$  8 ns,  $t_f \leq$  8 ns,  $t_f \leq$  9 ns,  $t_f$ 
  - B. C<sub>L</sub> includes probe and jig capacitance.

Figure 3. Driver Test Circuit and Voltage Waveforms



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_\Gamma \leq$  6 ns,  $t_f \leq$  7 ns,  $t_f \leq$  8 ns,  $t_f \leq$  8 ns,  $t_f \leq$  8 ns,  $t_f \leq$  8 ns,  $t_f \leq$  9 ns,  $t_f$ 
  - B. C<sub>1</sub> includes probe and jig capacitance.

Figure 4. Receiver Test Circuit and Voltage Waveforms



#### **TYPICAL CHARACTERISTICS**

DRIVER HIGH-LEVEL OUTPUT VOLTAGE vs **HIGH-LEVEL OUTPUT CURRENT** 5 V<sub>CC</sub> = 5 V 4.5 T<sub>A</sub> = 25°C VOH − High-Level Output Voltage − V 4 3.5 3 2.5 2 1.5 1 0.5 0 0 - 20 -40-60- 80 -100- 120 IOH - High-Level Output Current - mA

DRIVER
LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

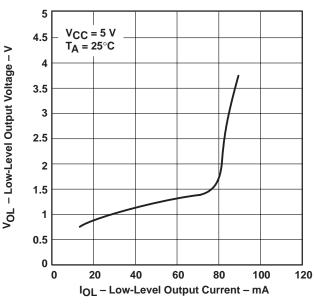
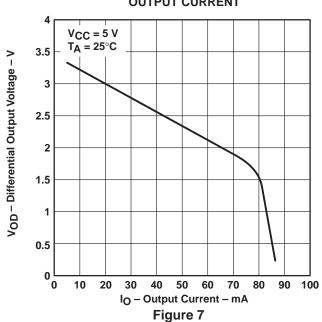


Figure 6

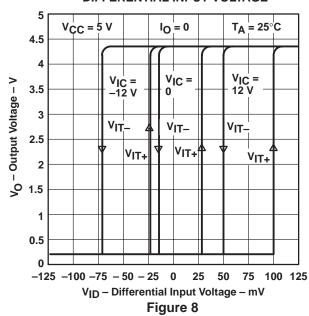
DRIVER
DIFFERENTIAL OUTPUT VOLTAGE

vs
OUTPUT CURRENT

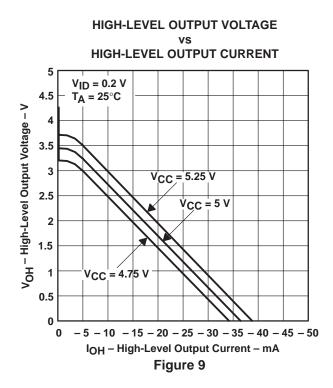
Figure 5

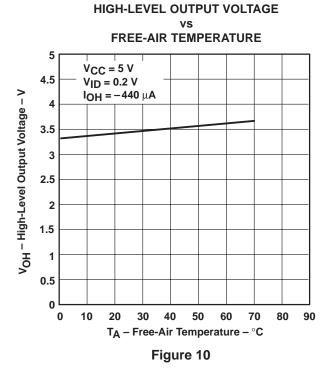


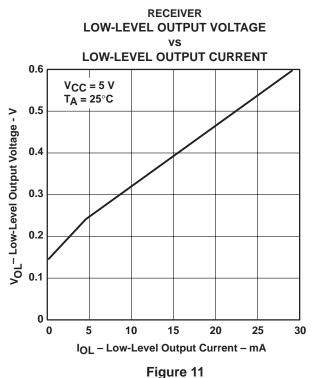
# RECEIVER OUTPUT VOLTAGE vs DIFFERENTIAL INPUT VOLTAGE

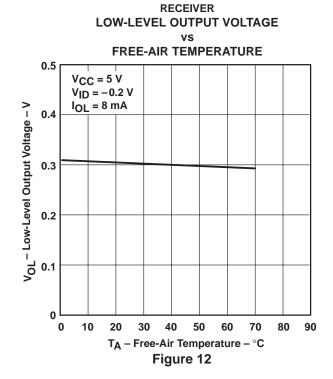


#### TYPICAL CHARACTERISTICS













ti.com 25-Feb-2005

#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN75179BD	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
SN75179BDR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
SN75179BP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN75179BPSR	ACTIVE	SO	PS	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

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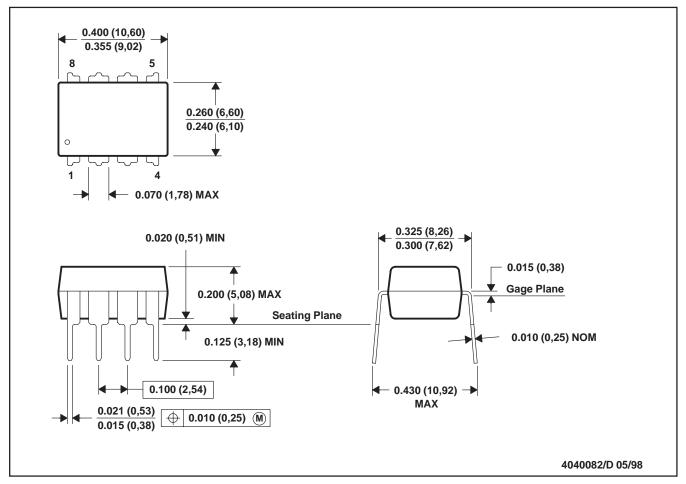
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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## P (R-PDIP-T8)

#### PLASTIC DUAL-IN-LINE



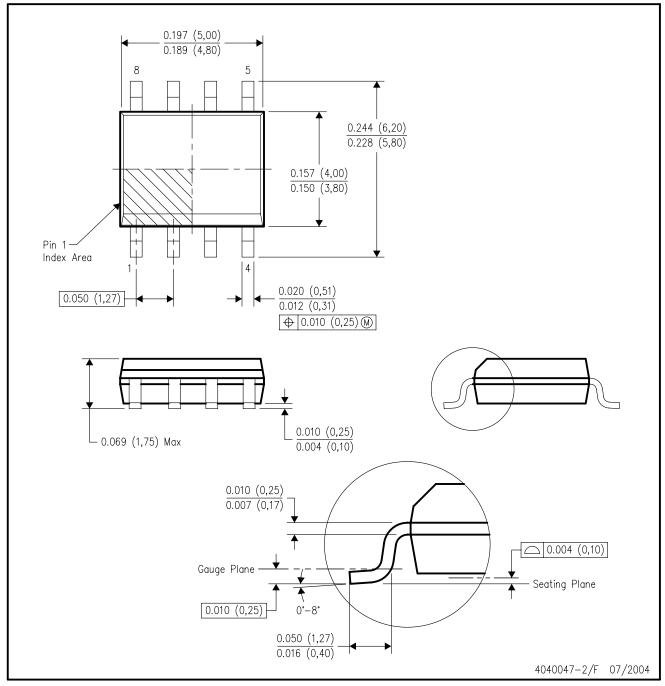
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to  $http://www.ti.com/sc/docs/package/pkg\_info.htm$ 

# D (R-PDSO-G8)

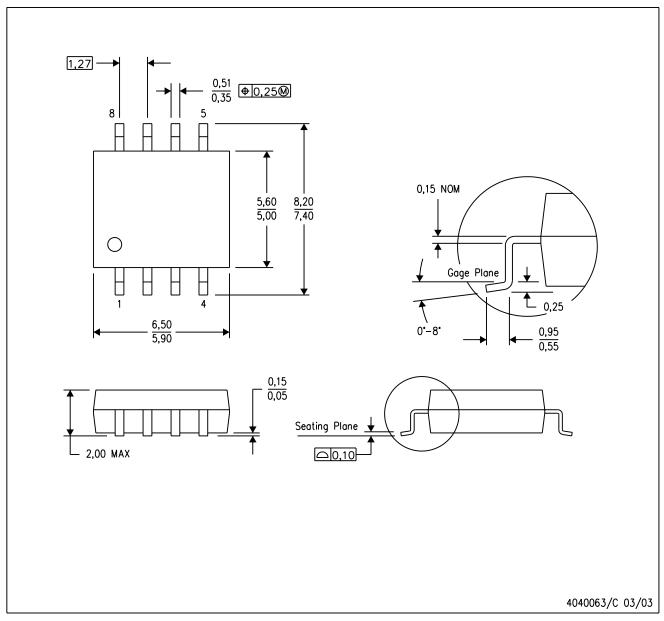
# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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